

Special Invited Session 06

Flexible Biosensors

Driven by advances in flexible materials, device architectures, and fabrication technologies, flexible sensors have experienced rapid development in recent years. By enabling conformal, lightweight, and mechanically compliant interfaces, these sensors can continuously monitor physical, chemical, and biological signals under dynamic deformation conditions. Such capabilities have led to broad applications in wearable devices, soft robotics, human-machine interfaces, and smart healthcare systems. This session focuses on recent progress and key findings in flexible sensor technologies, including novel materials, sensing mechanisms, device integration, and system-level applications.

Special Invited Session Chairs



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Nano/Micro Engineered and Molecular Systems

April 17-21, 2026 Chengdu, China

Paper Submission

For the initial submission, the authors can select one of the following two types:

- Type 1: full paper (4-6 pages)
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- Step 1: Please select the track “**Special Invited Sessions**” and click “**Continue**.”
- Step 2: After filling in the basic paper information, please select the topic “**SIS06 – Flexible Biosensors**.”



Important Dates

Initial Submission (Full Paper or Extended Abstract)	Jan. 31, 2026
Notification of Acceptance	Feb. 10, 2026
Late-News Submission Deadline	Feb. 28, 2026
Early Registration Deadline	Mar. 10, 2026
Presentation-Only Submission Deadline	Mar. 10, 2026
Final Submission Deadline	Mar. 10, 2026

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